



SEMICON Taiwan 2026 Exhibition Announcement

Takatori Corporation will exhibit at **SEMICON Taiwan 2026**, to be held from September 2 to 4, 2026. We sincerely look forward to welcoming you to our exhibition locations.

Exhibition Highlights

【 New Model: Panel Level Packaging Machine PLP-700 】

Takatori will present its latest Panel Level Packaging machine, the **PLP-700**, designed to support panel sizes up to **700 mm × 700 mm**, through panel display.

We will introduce advanced semiconductor manufacturing solutions centered on this latest PLP platform.

For detailed information about the PLP-700, please visit us at SEMICON Taiwan 2026.

Exhibition Locations:

- Toyo Adtec Pte. Ltd. Booth Hall 2, 1F, Booth No. Q5946

【 New Model: Multi Wire Saw for 12-inch SiC MWS-SiC12F 】

Takatori will also present its latest multi-wire saw, the **MWS-SiC12F**, designed for slicing large-diameter ingots up to 12 inches in diameter (maximum supported diameter: 14 inches), through panel displays.

For detailed information about the MWS-SiC12F, please visit us at SEMICON Taiwan 2026.

Exhibition Locations:

- Dong Rong Electronics Co.,Ltd. Hall 1, 4F, Booth No. R7121